Advanced Process Lab Services

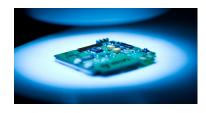












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MC-6795

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Optimize your assembly challenges to bring quality products to market faster.

Process Support and Development

- Process expertise for all assembly challenges: traditional/complex assembly, emerging technologies, advanced packaging, mechanical assembly
- Process development/audits for new and existing products; Formal report and recommendations
- Review of application assembly processes, materials and current yields
- Support for known process issues: materials, print, place, reflow
- In-depth materials analysis (PCBs, components, adhesives, solder paste, flux, encapsulation, materials, underfill)
- Advanced packaging expertise: wafer bumping, package assembly, ball attach
- Efficient, cost-effective and robust assembly processes

Product Development and Assembly Services

- Bring us your complex small-lot builds and expand your capabilities
- Prototyping and development, NPI through volume production
- State-of-the-art in-house production lines to build a full range of products
- Optimized assembly solutions (design, materials, process, pioneering equipment technology) for new and existing products
- Materials and components review and selection
- Design for Manufacture (DfM) and Design for Reliability (DfR)
- Maximize yields, minimize time to market